



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 2049  
Kazuto NISHIDA : Docket No. 99-0756A  
Serial No. 09/331,763 : Group Art Unit 3727  
Filed June 25, 1999 : Examiner J. Merek

METHOD AND APPARATUS FOR MOUNTING ELECTRONIC COMPONENT ON CIRCUIT BOARD

**DECLARATION UNDER RULE \$1.132**

Assistant Commissioner for Patents,  
Washington, D.C.

Sir:

I, Kazuto Nishida, say that:

I have the following education and employment history:

**Education History**

1984 (Graduation): Osaka Prefectural Technical College

1986 (Graduation of Faculty): Nagaoka University Of Technology, Faculty Engineering  
Department Of Electrical Engineering;

1988 (Graduation of master): Graduate School Of Nagaoka University Of Technology,  
Faculty Engineering Department Of Electrical Engineering.

**Employment History**

1988-1990: Matsushita Electric Industrial Co., LTD, Manufacturing Equipment Division;

1990-Present: Matsushita Electric Industrial Co., LTD, Corporate Production Engineering  
Division, Advanced JISSO Technology Laboratory.

RECEIVED  
NOV 21 2002  
TECHNOLOGY CENTER

During my employment with Matsushita Electric Industrial Co., LTD, I have worked, and continue to work, in the field of circuit boards.

I am familiar with materials of circuit boards and the effects that heat has thereon. Circuit boards made of a glass cloth base epoxy copper clad laminate, or made of a glass cloth base polyamide resin copper clad laminate, will soften upon being subjected to a temperature from 140° to 230° degrees centigrade for a time period that is between several seconds and twenty seconds.

I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issuing thereon.

Date: 8 . Nov . 2002

Signature: Kazuto Nishida  
Kazuto Nishida